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Jameco Part Number 884459

FEATURES AND SPECIFICATIONS

Features and Benefits

- Locking tang for secure housing retention

Reference Information

Packaging: Reel or bag

Use With: 51021

Mates With: 51025 and 50133

Designed In: Millimeters

Electrical

Voltage: 125V

Current: 1.0A

32 AWG—0.8A

Contact Resistance: 20mΩ max.

Dielectric Withstanding Voltage: 250V AC/1 min.

Insulation Resistance: 100 MΩ min.

Physical

Contact: Phosphor Bronze

Plating: Tin

Wire Range:

26 to 28 AWG—50079

28 to 32 AWG—50058

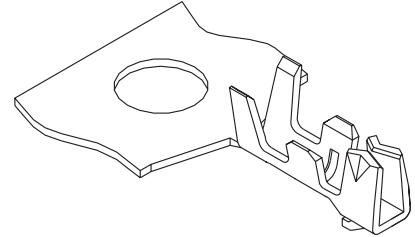
Insulation Range: 1.00mm dia. max.

Strip Length: 1.40 to 1.90mm

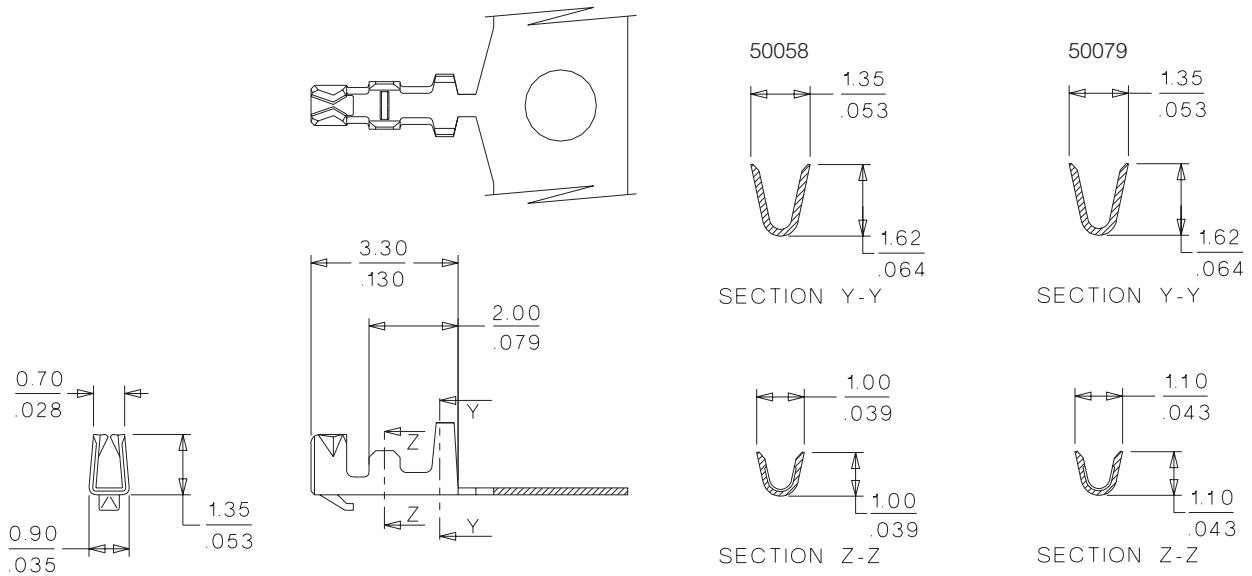
molex® 1.25mm (.049") Pitch Wire-to-Board and Wire-to-Wire Crimp Terminal

50079/50058

Female



Micro Connectors



ORDERING INFORMATION

Order No.	Wire Range AWG	Terminal
50079-8000	26 - 28	Reel
50058-8000	28 - 32	
50079-8100	26 - 28	Bag
50058-8100	28 - 32	



PRODUCT SPECIFICATION



LANGUAGE

JAPANESE
ENGLISH

[1. 適用範囲 SCOPE]

本仕様書は、
殿に納入する。

1.25mmピッチ SMT基板用 コネクタ について規定する。

This specification covers the 1.25mm PITCH WIRE TO BOARD CONNECTOR series.

[2. 製品名称及び型番 PRODUCT NAME AND PART NUMBER]

製品名称 Product Name		製品型番 Part Number
ターミナル Terminal (AWG #28-30)		50058-8*00
ターミナル Terminal (AWG #26-28)		50079-8*00
ハウジング Housing		51021-**00
ウェハー アッセンブリ Wafer Assembly (R/A)	無鉛 LEAD FREE	53261-**60
ウェハー アッセンブリ Wafer Assembly (R/A)	無鉛 LEAD FREE	53261-**93 (エンボステープ入り Embossed Tape Package)
ウェハー アッセンブリ Wafer Assembly (R/A)	無鉛 LEAD FREE	53261-**85 (エンボステープ入り, シリカゲル入り梱包 Embossed Tape Package Silicagel Pckage)

*: 図面参照 Refer to the drawing.

[3. 定格及び適用電線 RATINGS AND APPLICABLE WIRES]

項目 Item	規格 Standard	
最大許容電圧 Rated Voltage (MAX.)	125 V	
最大許容電流 及び適用電線 Rated Current (MAX.) and Applicable wires	AWG. #26	1.0 A
	AWG. #28	1.0 A
	AWG. #30	1.0 A
	AWG. #32	0.8 A
使用温度範囲 Ambient Temperature Range		-40°C ~ +85°C ^{*1}

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B		変更 REVISED J2007-0655 '06/09/06 M.NABEI				製品仕様書									
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REV.	DESCRIPTION					WRITTEN BY: S.MATSUZAKI	CHECKED BY: K.KASAHARA	APPROVED BY: T.YAMAGUCHI	DATE: YR/MO/DAY 2006/09/06						
DESIGN CONTROL J					STATUS										
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*1: 通電による温度上昇分も含む。
Including terminal temperature rise.

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[4. 性能 PERFORMANCE]

4-1. 電気的性能 ELECTRICAL PERFORMANCE

項 目 Item		条 件 Test Condition	規 格 Requirement
4-1-1	接触抵抗 Contact Resistance	コネクタを嵌合させ、開放電圧20mV 以下、 短絡電流 10mAにて測定する。 (JIS C5402 5.4) Mate connectors, measure by dry circuit, 20mV MAX., 10mA. (JIS C5402 5.4)	20 milliohm MAX.
4-1-2	絶縁抵抗 Insulation Resistance	コネクタを嵌合させ、隣接するターミナル間及び ターミナル、アース間に、DC 500V を印加し測 定する。 (JIS C5402 5.2/MIL-STD-202 試験法 302) Apply 500V DC between adjacent terminals or terminal and ground. (JIS C5402 5.2/MIL-STD-202 Method 302)	100 Megohm MIN.
4-1-3	耐電圧 Dielectric Strength	コネクタを嵌合させ、隣接するターミナル間及び ターミナル、アース間に、AC(rms)250V (実効 値) を 1 分間印加する。 (JIS C5402 5.1/MIL-STD-202 試験法 301) Apply 250V AC(rms) between adjacent terminals or terminal and ground for 1 minute. (JIS C5402 5.1/MIL-STD-202 Method 301)	異常なきこと No Breakdown
4-1-4	圧着部接触抵抗 Contact Resistance on Crimped Portion	ターミナルに適合電線を圧着し、開放電圧20mV 以下、短絡電流 10mA にて測定する。 Crimp the applicable wire to the terminal, and measure contact resistance by dry circuit, 20mV MAX., 10mA.	5 milliohm MAX.

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4-2. 機械的性能 MECHANICAL PERFORMANCE

項 目 Item		条 件 Test Condition	規 格 Requirement	
4-2-1	挿入力 及び抜去力 Insertion and Withdrawal Force	毎分 $25 \pm 3\text{mm}$ の速さで挿入、抜去を行 う。 Insert and withdraw connectors at the speed rate of $25 \pm 3\text{mm/minute}$.	第 7 参照 Refer to paragraph 7	
4-2-2	圧着部 引張り強度 Crimping Strength	圧着されたターミナルを治具に固定し、電 線を軸方向に毎分 $25 \pm 3\text{mm}$ の速さで引張 る。 (JIS C5402 6.8) Fix the crimped terminal, apply axial pull out force on the wire at the speed rate of $25 \pm 3\text{mm/minute}$. (JIS C5402 6.8)	AWG. #26	9.8 N {1.0kgf} MIN.
			AWG. #28	9.8 N {1.0kgf} MIN.
			AWG. #30	4.9 N {0.5kgf} MIN.
			AWG. #32	3.0 N {0.3kgf} MIN.
4-2-3	ターミナル 挿入力 Terminal Insertion Force	圧着されたターミナルをハウジングに 挿入する。 Insert the crimped terminal into the housing.	4.9 N {0.5kgf} MAX.	
4-2-4	ターミナル 保持力 Terminal/ Housing Retention Force	圧着されたターミナルをハウジングに装着 し、 電線を軸方向に毎分 $25 \pm 3\text{mm}$ の速さで 引張る。 Apply axial pull out force to the terminal assembled in the housing at the speed rate of $25 \pm 3\text{mm/minute}$.	4.9 N {0.5kgf} MIN.	
4-2-5	ピン保持力 Pin Retention Force	毎分 $25 \pm 3\text{mm}$ の速さで ピンを軸方 向に 押す。 Apply axial push force at the speed rate of $25 \pm 3\text{mm/minute}$.	4.9 N {0.5kgf} MIN.	

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4-3. その他 OTHERS

項 目 Item		条 件 Test Condition	規 格 Requirement	
4-3-1	繰り返し挿抜 Repeated Insertion/ Withdrawal	1分間に10回以下の速さで挿入、抜去を30回繰り返す。 When mated up to 30 cycles repeatedly by the rate of 10 cycles per minute.	接触抵抗 Contact Resistance	40 milliohm MAX.
4-3-2	温度上昇 Temperature Rise	コネクタを嵌合させ、最大許容電流を通電し、コネクタの温度上昇分を測定する。 (UL 498) Carrying rated current load. (UL 498)	温度上昇 Temperature Rise	30°C MAX.
4-3-3	耐振動性 Vibration	DC 1mA 通電状態にて、嵌合軸を含む互いに垂直な3方向に掃引割合10~55~10Hz/分全振幅 1.5mmの振動を各2時間加える。 (MIL-STD-202 試験法 201) Amplitude : 1.5mm P-P Sweep time : 10-55-10 Hz in 1 minute Duration : 2 hours in each x.y.z. axes (MIL-STD-202 Method 201)	外 観 Appearance	異状なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.
			瞬 断 Discontinuity	1.0 microsecond MAX.
4-3-4	耐衝撃性 Shock	DC 1mA 通電状態にて、嵌合軸を含む互いに垂直な6方向に490m/s ² {50G}, の衝撃を各3回加える。 (JIS C60068-2-27/MIL-STD-202 試験法213) 490m/s ² {50G}, 3 strokes in each X.Y.Z. axes. (JIS C60068-2-27/MIL-STD-202 Method 213)	外 観 Appearance	異状なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.
			瞬 断 Discontinuity	1.0 microsecond MAX.
4-3-5	耐熱性 Heat Resistance	コネクタを嵌合させ、85±2°Cの雰囲気中に96時間放置後取出し、1~2時間室温に放置する。 (JIS C60068-2-2/MIL-STD-202 試験法108) 85±2°C, 96 hours (JIS C60068-2-2/MIL-STD-202 Method 108)	外 観 Appearance	異状なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.

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項 目 Item		条 件 Test Condition	規 格 Requirement	
4-3-6	耐寒性 Cold Resistance	コネクタを嵌合させ、 $-40\pm 3^{\circ}\text{C}$ の雰囲気中に96時間放置後取出し、1～2時間室温に放置する。 (JIS C60068-2-1) $-40\pm 3^{\circ}\text{C}$, 96 hours (JIS C60068-2-1)	外 観 Appearance	異状なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.
4-3-7	耐湿性 Humidity	コネクタを嵌合させ、 $60\pm 2^{\circ}\text{C}$ 、相対湿度90～95%の雰囲気中に96時間放置後取出し、1～2時間室温に放置する。 (JIS C60068-2-3/MIL-STD-202 試験法103) Temperature : $60\pm 2^{\circ}\text{C}$ Relative Humidity : 90～95% Duration : 96 hours (JIS C60068-2-3/MIL-STD-202 Method 103)	外 観 Appearance	異状なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.
			耐 電 圧 Dielectric Strength	4-1-3項を 満足のこと Must meet 4-1-3
			絶縁抵抗 Insulation Resistance	10 Megohm MIN.
4-3-8	温度サイクル Temperature Cycling	コネクタを嵌合させ、 -55°C に30分、 $+105^{\circ}\text{C}$ に30分 これを1サイクルとし、5サイクル繰り返す。但し、温度移行時間は5分以内とする。試験後、1～2時間室温に放置する。 (JIS C0025) 5 cycles of : a) -55°C 30minute b) $+105^{\circ}\text{C}$ 30minute (JIS C0025)	外 観 Appearance	異状なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.
4-3-9	塩水噴霧 Salt Spray	コネクタを嵌合させ、 $35\pm 2^{\circ}\text{C}$ にて $5\pm 1\%$ 重量比の塩水を 48 ± 4 時間噴霧し、試験後常温で水洗いした後、室温で乾燥させる。 (JISC5028/MIL-STD-202 試験法101)	外 観 Appearance	異状なきこと No Damage

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		48±4 hours exposure to a salt spray from the 5±1% solution at 35±2°C. (JIS C5028/MIL-STD-202 Method 101)	接触抵抗 Contact Resistance	40 milliohm MAX.
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項 目 Item		条 件 Test Condition	規 格 Requirement	
4-3-10	耐亜硫酸ガス SO ₂ Gas	コネクタを嵌合させ、40±2°C にて 50±5ppm の亜硫酸ガス中に 24時間 放置する。 24 hours expose to 50±5ppm . SO ₂ gas at 40±2°C.	外 観 Appearance	異状なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.
4-3-11	耐アンモニア 性 NH ₃ Gas	コネクタを嵌合させ、濃度28%のアンモニア 水 を入れた容器中に40分間放置する。 (1Lに対して25mLの割合) 40 minutes exposure to NH ₃ gas evaporating from 28% Ammonia solution.	外 観 Appearance	異状なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.
4-3-12	半田付け性 Solderability	端子先端より0.5mm迄、及び金具先端を 245±3°Cの半田に2〜3秒浸す。 Soldering Time : 2 ~ 3 sec. Solder Temperature : 245±3°C 0.5mm from terminal tip and fitting nail tip.	濡れ性 Solder Wetting	浸漬面積の 95%以上 95% of immersed area must show no voids, pin holes
4-3-13	半田耐熱性 Resistance To Solder- Ing Heat	(リフロー時) 第6項参照。 <u>When reflowing</u> Repeat paragraph 6.	端子ガタ、割れ等 異状なきこと No Damage	
		(手半田) 端子先端より0.5mm迄、及び金具先端を、 370〜400°Cの半田ゴテにて、最大3±1 秒 加熱する。 <u>Soldering iron method</u> Soldering time : 3±1 sec. Solder temperature : 370〜400°C 0.5mm from terminal tip and fitting nail tip		

() : 参考規格 Reference

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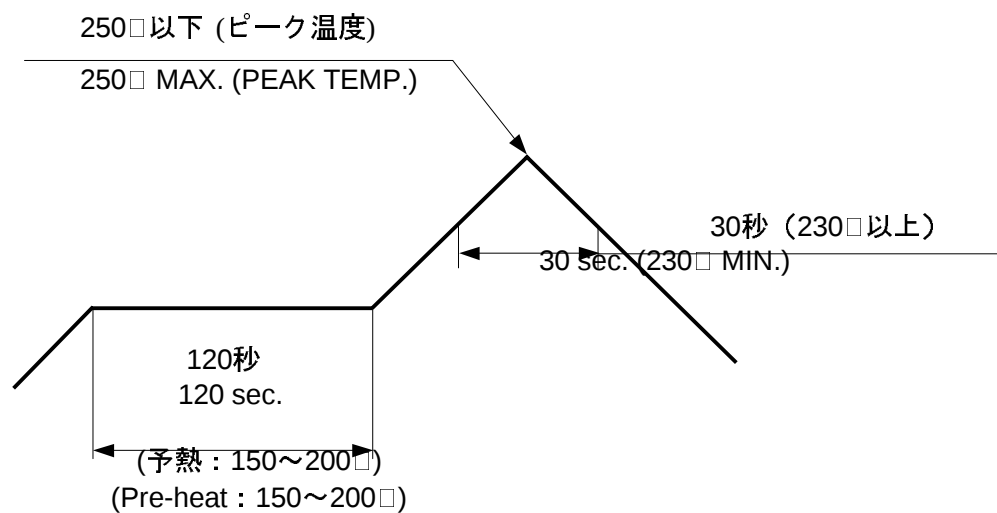
Standard

{ } : 参考単位 Reference Unit

[5. 外観形状、寸法及び材質 PRODUCT SHAPE, DIMENSIONS AND MATERIALS]

図面参照 Refer to the drawing.

[6. 赤外線リフロー条件 INFRARED REFLOW CONDITION]



温度条件グラフ
(温度は基板パターン面)

TEMPERATURE CONDITION GRAPH
(TEMPERATURE ON THE SURFACE OF P.C.BOARD PATTERN)

注記 ; 本リフロー条件に関しては、リフロー装置及び基板などにより条件が異なりますので、
事前にリフロー評価の確認をお願い致します。

NOTE ; Please check the reflow soldering condition by your own devices beforehand.
Because the condition changes by the soldering devices, P.C.Boards, and so on.

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[7. 挿入力及び抜去力 INSERTION / WITHDRAWAL FORCE]

極数 No. of CKT.	単位 Unit	挿入力 (最大値) Insertion force (MAX.)			抜去力 (最小値) Withdrawal force (MIN.)		
		初回 1st	6回目 6th	30回目 30th	初回 1st	6回目 6th	30回目 30th
2	N { kgf }	19.6 { 2.0 }	17.6 { 1.8 }	15.6 { 1.6 }	2.8 { 0.28 }	2.3 { 0.23 }	1.8 { 0.18 }
3	N { kgf }	24.5 { 2.5 }	22.5 { 2.3 }	20.5 { 2.1 }	3.0 { 0.30 }	2.5 { 0.25 }	2.0 { 0.20 }
4	N { kgf }	29.4 { 3.0 }	27.4 { 2.8 }	25.4 { 2.6 }	3.3 { 0.33 }	2.8 { 0.28 }	2.3 { 0.23 }
5	N { kgf }	34.3 { 3.5 }	32.3 { 3.3 }	30.3 { 3.1 }	3.8 { 0.38 }	3.3 { 0.33 }	2.8 { 0.28 }
6	N { kgf }	39.2 { 4.0 }	37.2 { 3.8 }	35.2 { 3.6 }	4.3 { 0.43 }	3.8 { 0.38 }	3.3 { 0.33 }
7	N { kgf }	44.1 { 4.5 }	42.1 { 4.3 }	40.1 { 4.1 }	4.7 { 0.48 }	4.3 { 0.43 }	3.8 { 0.38 }
8	N { kgf }	49.0 { 5.0 }	47.0 { 4.8 }	45.0 { 4.6 }	5.2 { 0.53 }	4.7 { 0.48 }	4.3 { 0.43 }
9	N { kgf }	53.9 { 5.5 }	51.9 { 5.3 }	49.9 { 5.1 }	5.5 { 0.56 }	5.0 { 0.51 }	4.5 { 0.46 }
10	N { kgf }	58.8 { 6.0 }	56.8 { 5.8 }	54.8 { 5.6 }	5.8 { 0.59 }	5.3 { 0.54 }	4.8 { 0.49 }
11	N { kgf }	63.7 { 6.5 }	61.7 { 6.3 }	59.7 { 6.1 }	6.1 { 0.62 }	5.6 { 0.57 }	5.1 { 0.52 }
12	N { kgf }	68.6 { 7.0 }	66.6 { 6.8 }	64.6 { 6.6 }	6.4 { 0.65 }	5.9 { 0.60 }	5.4 { 0.55 }
13	N { kgf }	73.5 { 7.5 }	71.5 { 7.3 }	69.5 { 7.1 }	6.7 { 0.68 }	6.2 { 0.63 }	5.7 { 0.58 }
14	N { kgf }	78.4 { 8.0 }	76.4 { 7.8 }	74.4 { 7.6 }	7.0 { 0.71 }	6.5 { 0.66 }	6.0 { 0.61 }

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15	N { kgf }	83.3 { 8.5 }	81.3 { 8.3 }	79.3 { 8.1 }	7.3 { 0.74 }	6.8 { 0.69 }	6.3 { 0.64 }
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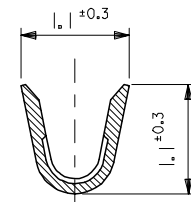
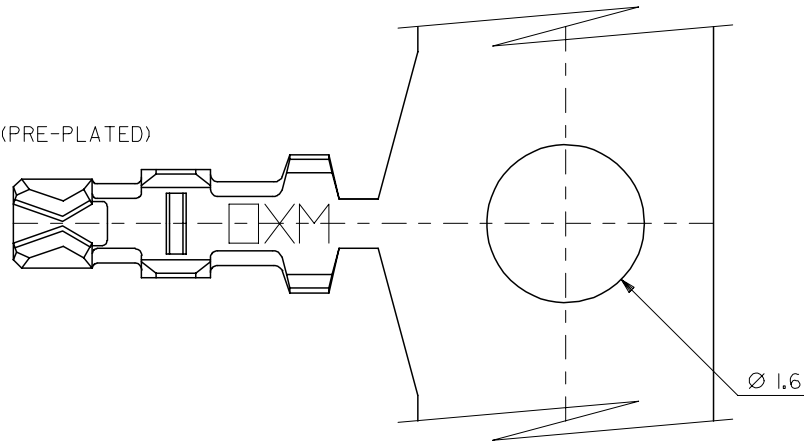
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A	RELEASED	'02/07/05	J2003-0019	S.MATSUZAKI	K.YAMAGUHI
B	REVISED	'06/09/06	J2007-0655	M.NABEI	K.TOYODA

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	DOCUMENT NUMBER PS-51021-022			FILE NAME PS51021022.doc
EN-37-1(019)				

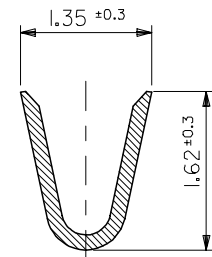
10 9 8 7 6 5 4 3 2 1

注記
NOTES

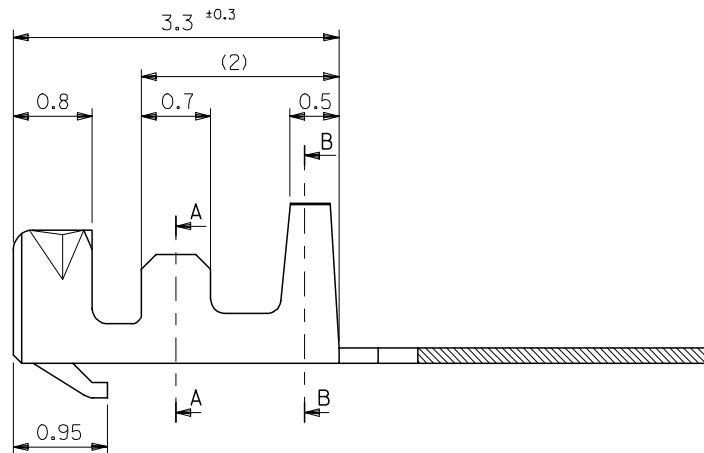
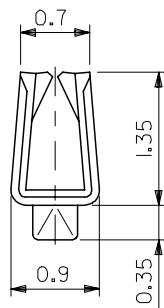
1. 適合ハウジング：51021シリーズ
APPLICABLE HOUSING : 51021 SERIES
2. メッキ仕様 PLATING
錫 0.9 μ m MIN. リフロー処理 (前メッキ)
TIN 0.9 μ m MIN. REFLOW TREATMENT (PRE-PLATED)



SECT. A-A



SECT. B-B



50079-8100	バラ状 LOOSE
50079-8000	連鎖状 CHAIN
MATERIAL NO.	端子形状 FORM

MODEL NO. 50079-8*00

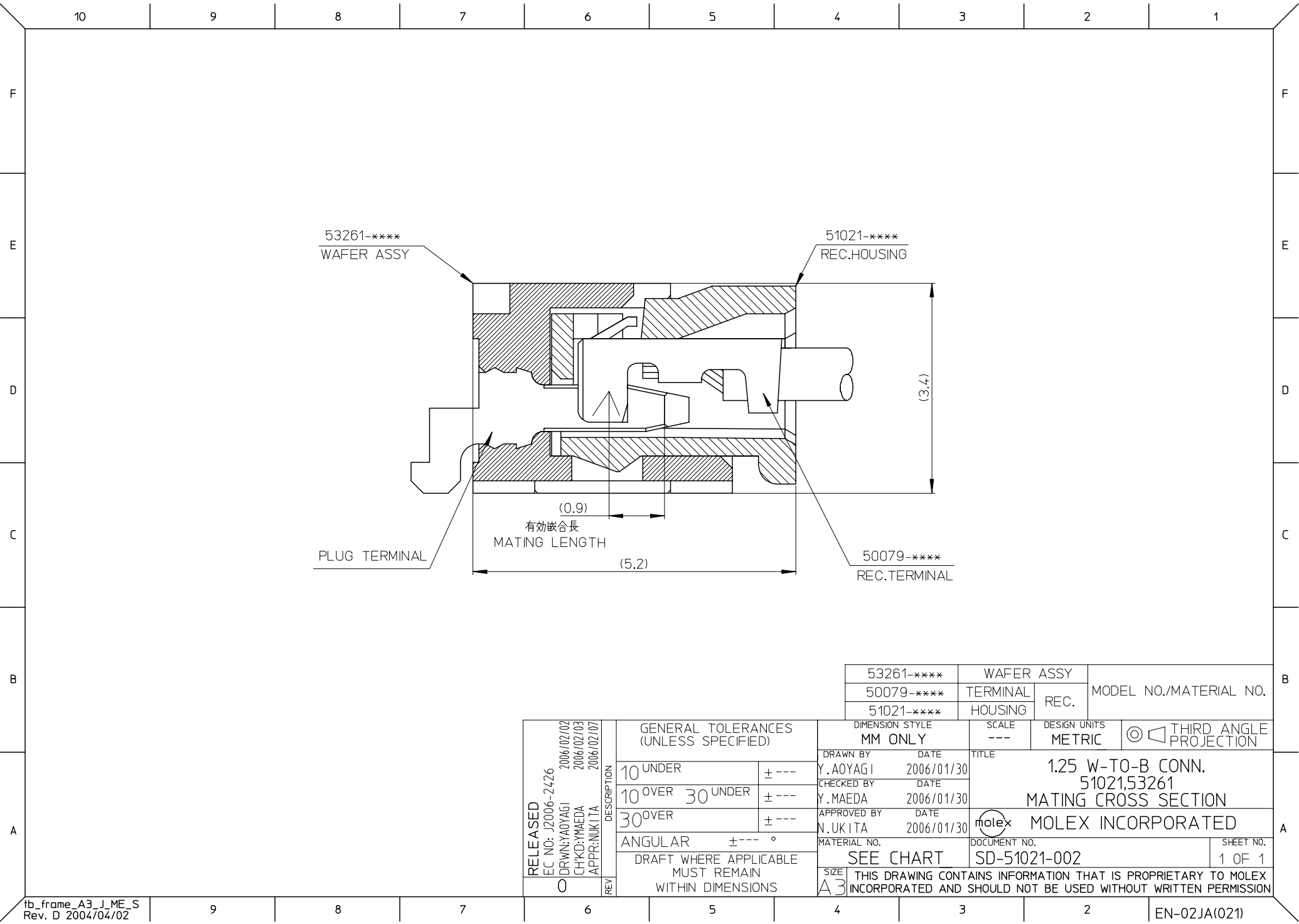
材料 MATERIAL	リン青銅 (t=0.15) PHOSPHOR BRONZE
仕上げ FINISH	—#—
適用電線範囲 WIRE RANGE	AWG #26-28
被覆外径 INS. RANGE	φ0.5-1.04

REVISED EC NO: J2005-1535 DRAWN: SUZUKI CHKD: KATO APPR: NUKITA	2004/11/30 2004/11/30 2004/12/06	DESCRIPTION REV
G		

GENERAL TOLERANCES (UNLESS SPECIFIED)	
10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE MM ONLY	
DRAWN BY HHIRAMOT	DATE 92/10/21
CHECKED BY SKUNISHI	DATE 98/07/07
APPROVED BY MFUKUSHI	DATE 98/07/07
MATERIAL NO.	
SIZE A3	

SCALE 20:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
TITLE 1.25 WIRE TO BOARD CONN. CRIMP REC. TERMINAL -LEAD FREE-		
MOLEX INCORPORATED		
DOCUMENT NO. SD-50079-001		SHEET NO. 1 OF 1
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRWN:YAOYAGI 2006/02/02 CHKD:YMAEDA 2006/02/03 APPR:NUKITA 2006/02/07 REV 0	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	Y.AOYAGI	2006/01/30	TITLE 1.25 W-TO-B CONN. 51021,53261 MATING CROSS SECTION				
		10 OVER 30 UNDER	± ---	Y.MAEDA	2006/01/30					
		30 OVER	± ---	N.UKITA	2006/01/30	MOLEX INCORPORATED				
		ANGULAR ± --- °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-51021-002		1 OF 1			
	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								